

INTERFACE PROBES

Z585

For Testing von ICs on PCBs (Test Jet)

Centers (mm/mil)	9,50 / 374
Current	3,0 A
R typ	30 mOhm
Temperature	-20°C...+80°C

Spring Force (cN ±20%)		
Version	Preload	Nominal
Standard	50	100
S1	50	100

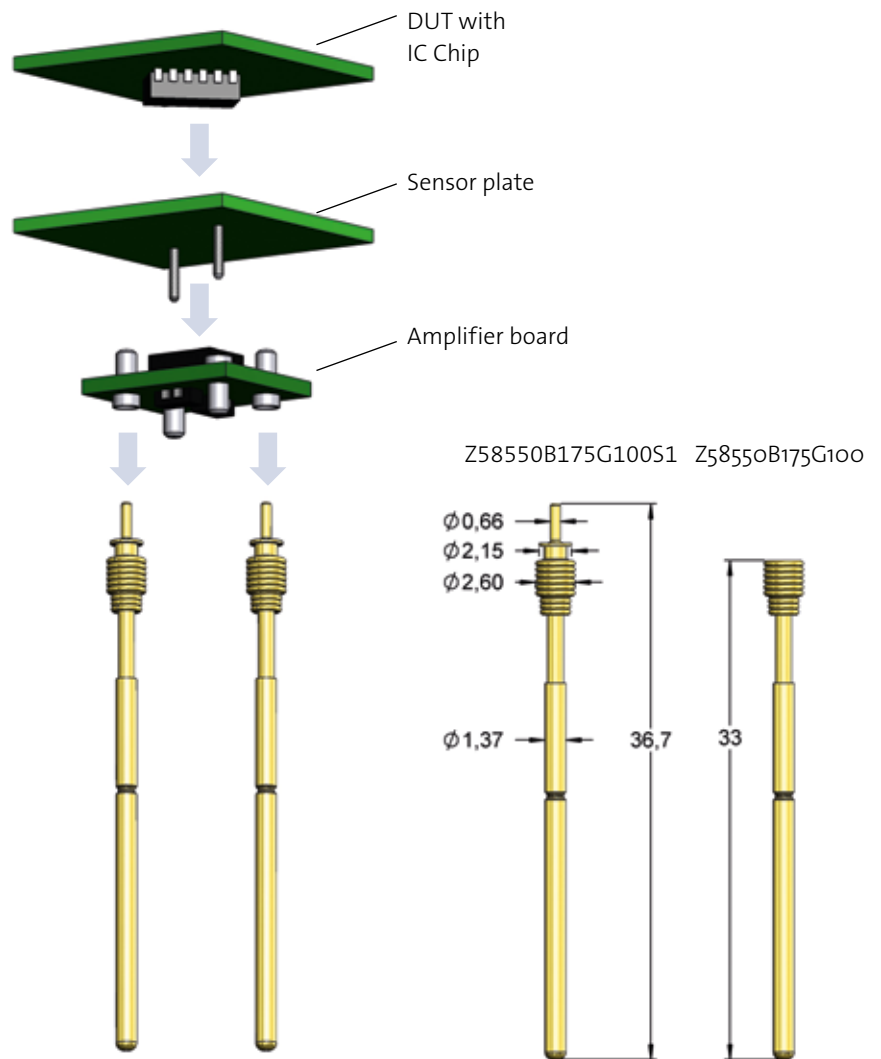
Travel (mm)		
Version	Nominal	Maximum
Standard	5,0	9,6
S1	5,0	9,6

Materials and Plating	
Plunger	BeCu, gold plated
Barrel	Nickel silver, gold plated
Spring	Music wire, silver plated
Receptacle	Nickel silver, gold plated

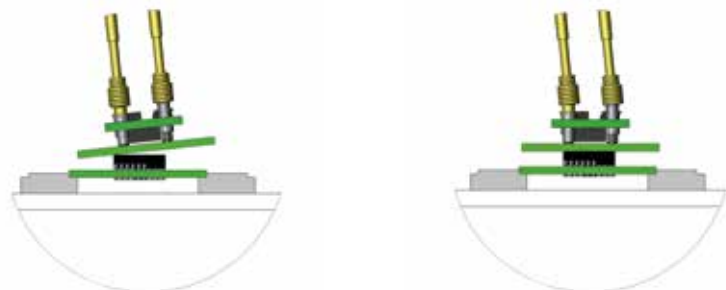
Accessories	
Insertion tool receptacle	FEWZ-774E0
Insertion tool probe	FDWZ-100

Drill size (mm)	
H774...	2,98 - 2,99

Projection Height (mm)	
H774... with F796	15,2



The Z585/Z588 is a special probe for non-contact gauging of IC-components. The contact probes are used in pairs as flexible holder for the sensor plate. This measuring principle is known as „TestJet“ in the Agilent test system and as “Frame Scan“ in the Teradyne test system. Mounting receptacles see H100.



The flexible contact head with spring element ensures an optimal adjustment of the sensor plate on the IC or component.

Order Code	Description
Z58550B175G100S1	Test jet spring contact probe wit spiral spring head (Agilent)
Z58550B175G100	Test jet spring contact probe with spiral spring head (Digitaltest)

Capacitive Sensors and Accessories

Test system	Description	Order code	Unit of trading
System Agilent („Testjet“ und „VTEP“)			
Testjet	Signal Conditioner Board* (Mux Board)	2100175	1
	Signal Conditioner Board* (Mux+REF B-Revision)	2100191	1
	Testjet Amplifier incl. 2 probes 2100830 bulk	2100176	1
	Testjet Amplifier incl. 2 probes Z58550B175G130S1 bulk	2101350	1
	Testjet Amplifier without probes	2102310	1
	Sensor Plates 9,5x12 mm (0,375x0,475 inch), usable area 5,5x10,3 mm (0,217x0,405 inch) SO14	2100823	10
	Sensor Plates 10,8x14,6 mm (0,475x0,575 inch) SO20	2100824	10
	Sensor Plates 30x30 mm (1,2x1,2 inch)	2100825	1
	Sensor Plates 64x64 mm (2,5x2,5 inch)	2100826	1
	Sensor Plates 12,5x158 mm (0,5x6,1 inch)	2100827	1
	Sensor Plates* 30x30 mm (1,2x1,2 inch)	2100179	1
	Sensor Plates* 64x64 mm (2,5x2,5 inch)	2100180	1
	Sensor Plates* 12,5x158 mm (0,5x6,1 inch)	2100190	1
	Small Testjet Amplifier* incl. 2 probes 2100822 bulk	2100192	1
	Small Sensor Plates* B-C Size 4x6,4 mm also for VTEP	2100193	10
	Small Sensor Plates* D Size 5x7,6 mm also for VTEP	2100194	10
	Set: Small Testjet Amplifier* incl. 2 probes 2100822 soldered and Sensor Plate B-C-Size soldered	40400146	1
	Set: Small Testjet Amplifier* incl. 2 probes 2100822 soldered and Sensor Plate D-Size soldered	40400147	1
	Set: Small Testjet Amplifier* incl. 2 probes 2100822 soldered without Sensor Plate	40400104	1
VTEP	VTEP Signal Conditioner Board* (Mux-Board)	2101126	1
	VTEP Signal Conditioner Board* (Mux+REF)	2101127	1
	VTEP Testjet Amplifier* incl. 2 probes 2100830 bulk	2101128	1
	VTEP Testjet Amplifier* incl. 2 probes Z58550B175G130S1 bulk	2102041	1
	VTEP Testjet Amplifier* without probes	2102275	1
	VTEP Sensor Plates* 30x30 mm (1,2x1,2 inch)	2101131	1
	VTEP Sensor Plates* 64x64 mm (2,5x2,5 inch)	2101132	1
	VTEP Sensor Plates* 12,5x158 mm (0,5x6,1 inch)	2101130	1
	VTEP Small Testjet Amplifier* incl. 2 probes 2100822 bulk	2101133	1
	VTEP Small Sensor Plates, see above		
	* orig. Agilent		
System Teradyne („Framescan“ und „Capscan“)			
	Teradyne Mux-Board	4-805960	1
Framescan	Teradyne Framescan Amplifier (higher amplification factor than System Agilent Testjet Amplifier) - alternatively also System Agilent Testjet Amplifier (not for VTEP) - Sensor Plates identical to System Agilent	2101970	1
Capscan	identical to System Agilent Small Testjet parts (not for VTEP, see above)		
System Digitaltest („Opens Check“)			
	Digitaltest Opens Check Board (Amplifier)	2100199	
	Passive Sensor Connection Board incl. 2 probes Z58550B175G130	4-806448	
	Sensor Plates identical System Agilent, see above		
	Opens Check probe with FM spiral head Z58550B175G130	Z58550B175G130	10
	Plug-in part for FM spiral spring probe SO585B02G	SO585B02G	10